

**Qualification Results Summary of ADXL362, ADXL363 Sensor Wafers  
on 8" MEMS Only Process at TSMC fab3**

<b>TEST</b>	<b>CONDITIONS</b>	<b>SAMPLE SIZE</b>	<b>RESULTS</b>
Early Life Fail (ELF)	<b>MIL-STD-883 M1015</b>	<b>3x800</b>	<b>PASS</b>
Highly Accelerated Stress Test (HAST)*	<b>JEDEC JESD22-A110</b>	<b>3x77</b>	<b>PASS</b>
High Temperature Operating Life (HTOL)*	<b>JEDEC JESD22-A108</b>	<b>3x77</b>	<b>PASS</b>
Temperature Cycle (TC)*	<b>JEDEC JESD22-A104</b>	<b>3x77</b>	<b>PASS</b>
Unbiased Highly Accelerated Stress Test (UHAST) *	<b>JEDEC JESD22-A118</b>	<b>3x77</b>	<b>PASS</b>
Low Temperature Storage (LTS)	<b>JEDEC JESD22-A119</b>	<b>3x77</b>	<b>PASS</b>
Low Temperature Operating Life (LTOL)	<b>JEDEC JESD22-A108</b>	<b>3x77</b>	<b>PASS</b>
High Temperature Storage Life (HTSL)	<b>JEDEC JESD22-A103</b>	<b>3x77</b>	<b>PASS</b>
Mechanical Shock Powered	<b>IEC 68 Part 2-27 Testgroup Ea</b>	<b>4x10</b>	<b>PASS</b>
1.2m Random Drop	<b>CAM0091</b>	<b>7x35</b>	<b>PASS</b>
1.2m Guided Drop	<b>IEC 60068-2-32</b>	<b>5x5</b>	<b>PASS</b>
Group D Sub Group 4	<b>MIL-STD-883 M5005</b>	<b>3x15</b>	<b>PASS</b>
FICDM	<b>JESD22-C101</b>	<b>1x3</b>	<b>PASS</b>
HBM	<b>ESDA/JEDEC JS-001-2011</b>	<b>1x3</b>	<b>PASS</b>
MM	<b>JESD22-A115</b>	<b>1x3</b>	<b>PASS</b>
LU	<b>JEDEC-JESD78</b>	<b>1x6</b>	<b>PASS</b>

\*Preconditioned per JEDEC/IPC J-STD-020